DATA SHEET

NEC

HETERO JUNCTION FIELD EFFECT TRANSISTOR
NE3509M04

L TO S BAND LOW NOISE AMPLIFIER
N-CHANNEL HJ-FET

FEATURES

- Super low noise figure and high associated gain
  NF = 0.4 dB TYP., G_a = 17.5 dB TYP. @ f = 2 GHz, V_{DS} = 2 V, I_D = 10 mA
- Flat-lead 4-pin thin-type super minimold (M04) package

APPLICATIONS

- Satellite radio (SDARS, DMB, etc.) antenna LNA
- GPS antenna LNA
- Low noise amplifier for microwave communication system

ORDERING INFORMATION

Part Number	Order Number	Package	Quantity	Marking	Supplying Form
NE3509M04	NE3509M04-A	Flat-lead 4-pin thin-type super minimold (M04) (Pb-Free)	50 pcs (Non reel)	V80	• 8 mm wide embossed taping • Pin 1 (Source), Pin 2 (Drain) face the perforation side of the tape
NE3509M04-T2	NE3509M04-T2-A		3 kpcs/reel		

Remark To order evaluation samples, contact your nearby sales office.
Part number for sample order: NE3509M04

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C)

Parameter	Symbol	Ratings	Unit
Drain to Source Voltage	V_{DS}	4.0	V
Gate to Source Voltage	V_{GS}	–3.0	V
Drain Current	I_D	I_{DSS}	mA
Gate Current	I_G	200	μA
Total Power Dissipation	P_{tot} Note	150	mW
Channel Temperature	T_{ch}	+150	°C
Storage Temperature	T_{stg}	–65 to +150	°C

Note Mounted on 1.08 $cm^2 \times$ 1.0 mm (t) glass epoxy PCB

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

Document No. PG10608EJ01V0DS (1st edition)
Date Published April 2006 NS CP(K)
Printed in Japan

RECOMMENDED OPERATING CONDITIONS (T_A = +25°C)

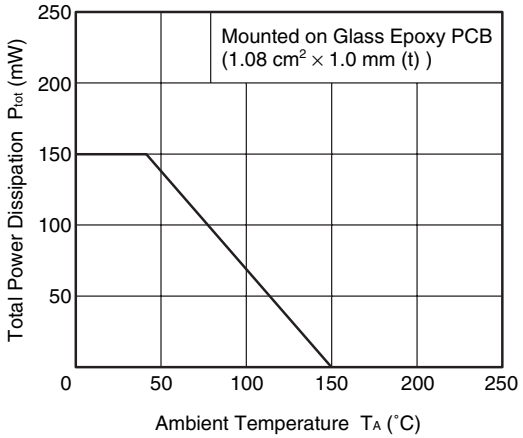
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Drain to Source Voltage	V_{DS}	–	2	3	V
Drain Current	I_D	–	10	20	mA
Input Power	P_{in}	–	–	0	dBm

ELECTRICAL CHARACTERISTICS (T_A = +25°C, unless otherwise specified)

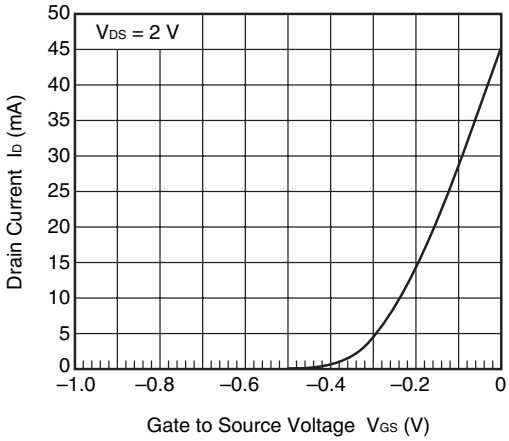
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Gate to Source Leak Current	I_{GSO}	V_{GS} = –3 V	–	0.5	10	μA
Saturated Drain Current	I_{DSS}	V_{DS} = 2 V, V_{GS} = 0 V	30	45	60	mA
Gate to Source Cutoff Voltage	$V_{GS (off)}$	V_{DS} = 2 V, I_D = 50 μA	–0.25	–0.5	–0.75	V
Transconductance	g_m	V_{DS} = 2 V, I_D = 10 mA	80	–	–	mS
Noise Figure	NF	V_{DS} = 2 V, I_D = 10 mA, f = 2 GHz	–	0.4	0.7	dB
Associated Gain	G_a		16	17.5	–	dB
Gain 1 dB Compression Output Power	$P_{O (1 dB)}$	V_{DS} = 2 V, I_D = 10 mA (Non-RF), f = 2 GHz	–	11	–	dBm

TYPICAL CHARACTERISTICS (T_A = +25°C, unless otherwise specified)

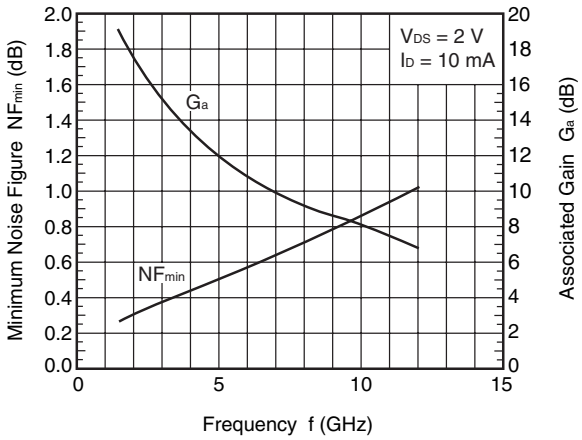
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



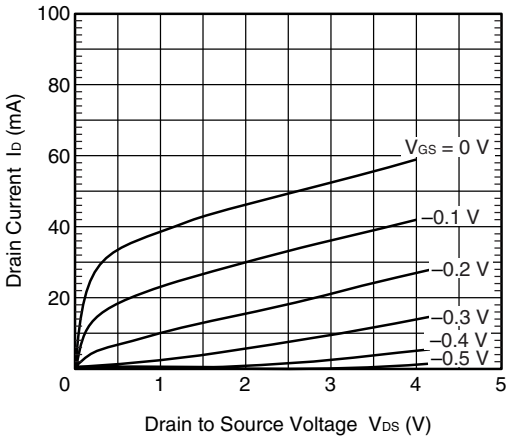
DRAIN CURRENT vs. GATE TO SOURCE VOLTAGE



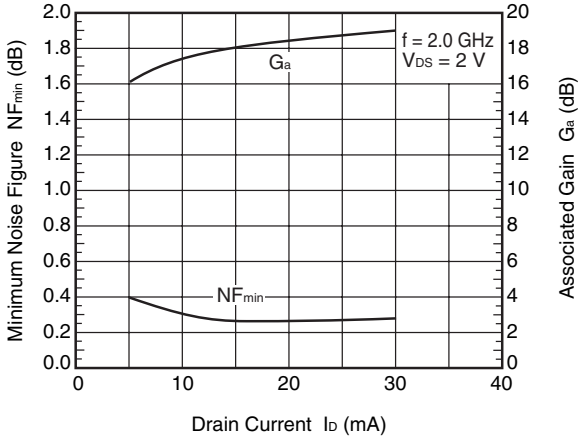
MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. FREQUENCY



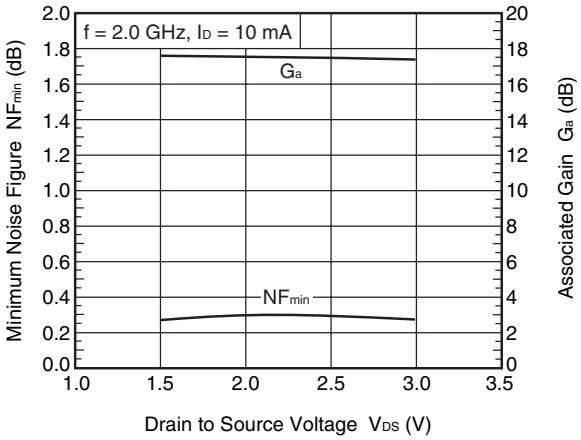
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. DRAIN CURRENT

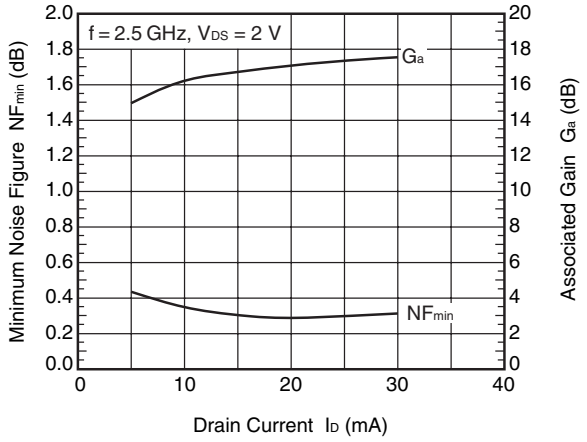


MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. DRAIN TO SOURCE VOLTAGE

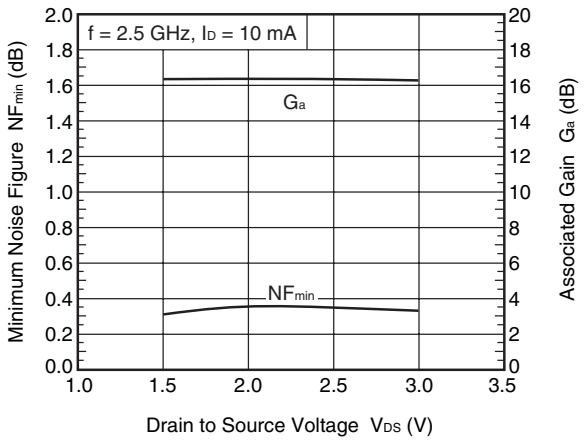


Remark The graphs indicate nominal characteristics.

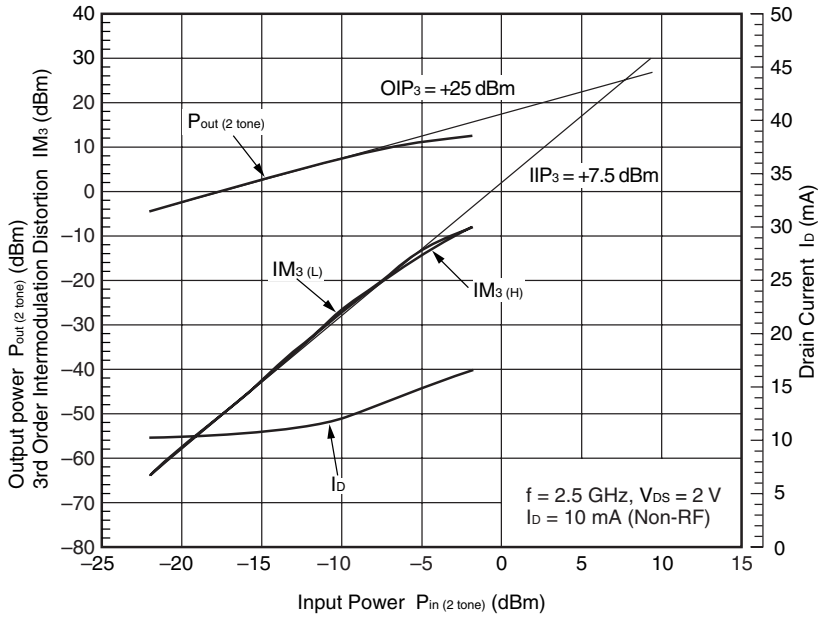
MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. DRAIN CURRENT



MINIMUM NOISE FIGURE, ASSOCIATED GAIN vs. DRAIN TO SOURCE VOLTAGE



OUTPUT POWER, IM3, DRAIN CURRENT vs. INPUT POWER



Remark The graphs indicate nominal characteristics.

S-PARAMETERS

S-parameters/Noise parameters are provided on our web site in a form (S2P) that enables direct import to a microwave circuit simulator without keyboard input.

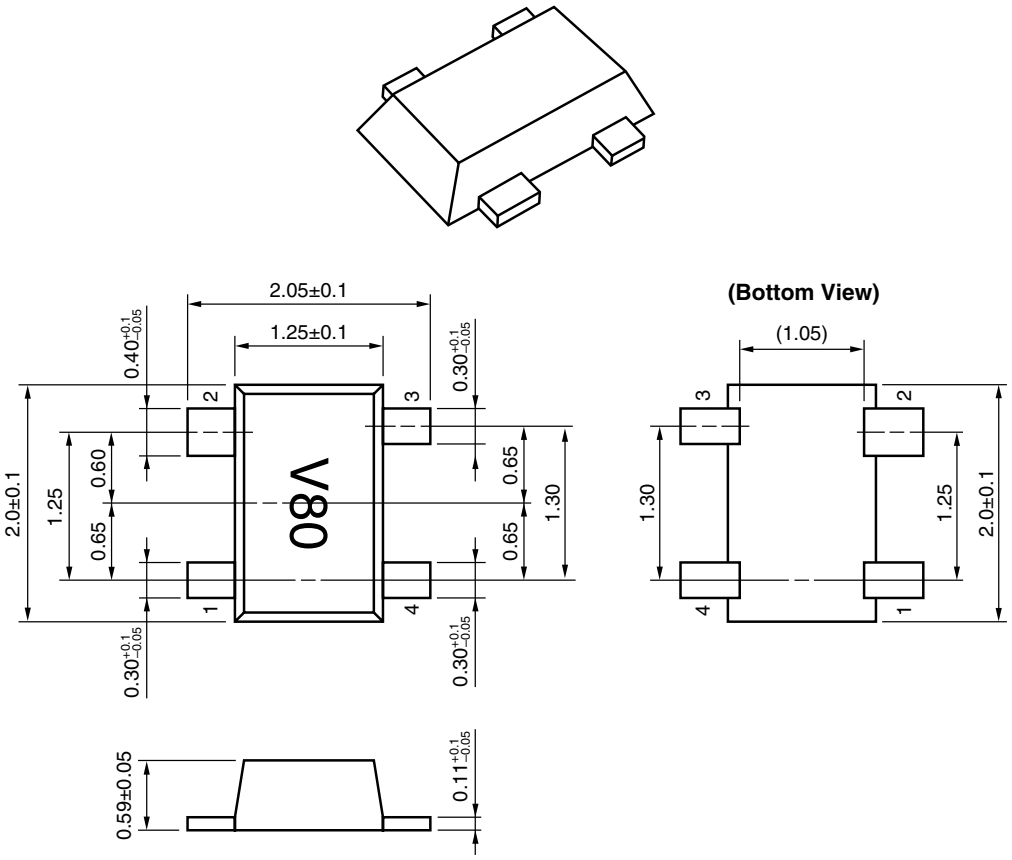
Click here to download S-parameters.

[RF and Microwave] → [Device Parameters]

URL http://www.ncsd.necel.com/

PACKAGE DIMENSIONS

FLAT-LEAD 4-PIN THIN-TYPE SUPER MINIMOLD (M04) (UNIT: mm)

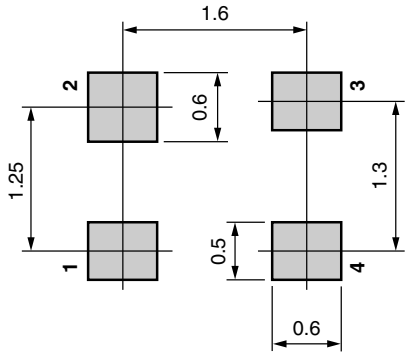


PIN CONNECTIONS

1. Source
2. Drain
3. Source
4. Gate

MOUNTING PAD DIMENSIONS (REFERENCE ONLY)

FLAT-LEAD 4-PIN THIN-TYPE SUPER MINIMOLD (M04) PACKAGE (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

- **The information in this document is current as of April, 2006. The information is subject to change without notice. For actual design-in, refer to the latest publications of NEC Electronics data sheets or data books, etc., for the most up-to-date specifications of NEC Electronics products. Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.**
- No part of this document may be copied or reproduced in any form or by any means without the prior written consent of NEC Electronics. NEC Electronics assumes no responsibility for any errors that may appear in this document.
- NEC Electronics does not assume any liability for infringement of patents, copyrights or other intellectual property rights of third parties by or arising from the use of NEC Electronics products listed in this document or any other liability arising from the use of such products. No license, express, implied or otherwise, is granted under any patents, copyrights or other intellectual property rights of NEC Electronics or others.
- Descriptions of circuits, software and other related information in this document are provided for illustrative purposes in semiconductor product operation and application examples. The incorporation of these circuits, software and information in the design of a customer's equipment shall be done under the full responsibility of the customer. NEC Electronics assumes no responsibility for any losses incurred by customers or third parties arising from the use of these circuits, software and information.
- While NEC Electronics endeavors to enhance the quality, reliability and safety of NEC Electronics products, customers agree and acknowledge that the possibility of defects thereof cannot be eliminated entirely. To minimize risks of damage to property or injury (including death) to persons arising from defects in NEC Electronics products, customers must incorporate sufficient safety measures in their design, such as redundancy, fire-containment and anti-failure features.
- NEC Electronics products are classified into the following three quality grades: "Standard", "Special" and "Specific".
  The "Specific" quality grade applies only to NEC Electronics products developed based on a customer-designated "quality assurance program" for a specific application. The recommended applications of an NEC Electronics product depend on its quality grade, as indicated below. Customers must check the quality grade of each NEC Electronics product before using it in a particular application.
  "Standard": Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots.
  "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support).
  "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

The quality grade of NEC Electronics products is "Standard" unless otherwise expressly specified in NEC Electronics data sheets or data books, etc. If customers wish to use NEC Electronics products in applications not intended by NEC Electronics, they must contact an NEC Electronics sales representative in advance to determine NEC Electronics' willingness to support a given application.

(Note)
(1) "NEC Electronics" as used in this statement means NEC Electronics Corporation and also includes its majority-owned subsidiaries.
(2) "NEC Electronics products" means any product developed or manufactured by or for NEC Electronics (as defined above).

M8E 02. 11-1

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.

▶**For further information, please contact**

NEC Compound Semiconductor Devices Hong Kong Limited
E-mail: contact@ncsd-hk.necel.com
Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309
Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859
Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209

NEC Electronics (Europe) GmbH http://www.eu.necel.com/
TEL: +49-211-6503-0 FAX: +49-211-6503-1327

California Eastern Laboratories, Inc. http://www.cel.com/
TEL: +1-408-988-3500 FAX: +1-408-988-0279

Compound Semiconductor Devices Division
NEC Electronics Corporation
URL: http://www.ncsd.necel.com/

0604